Global Thin Wafer Processing and Dicing Equipment Market 2022-2028

https://marketpublishers.com/r/GE66DF75D19EEN.html
Date: December 2022
Pages: 62
Price: US$ 2,950.00 (Single User License)
ID: GE66DF75D19EEN

Abstracts

The global thin wafer processing and dicing equipment market size is projected to grow by USD 272.0 million from 2022 to 2028, registering a CAGR of 6.3 percent, according to a new report by Gen Consulting Company.

The report covers market size and growth, segmentation, regional breakdowns, competitive landscape, trends and strategies for global thin wafer processing and dicing equipment market. It traces the market's historic and forecast market growth. The report identifies top segments for opportunities and strategies based on market trends and leading competitors' approaches. This study also provides an analysis of the impact of the COVID-19 crisis on the thin wafer processing and dicing equipment industry.

This industry report offers market estimates and forecasts of the global market, followed by a detailed analysis of the type, wafer size, application, and region. The global market for thin wafer processing and dicing equipment can be segmented by type: thinning equipment, dicing equipment. The thinning equipment segment captured the largest share of the market in 2021. Thin wafer processing and dicing equipment market is further segmented by wafer size: less than 4 inch, 5 inch and 6 inch, 8 inch, 12 inch. The 8 inch segment held the largest share of the global thin wafer processing and dicing equipment market in 2021 and is anticipated to hold its share during the forecast period. Based on application, the thin wafer processing and dicing equipment market is segmented into: memory and logic, MEMS device, power device, CMOS image sensor, RFID. In 2021, the CMOS image sensor segment made up the largest share of revenue generated by the thin wafer processing and dicing equipment market. On the basis of region, the thin wafer processing and dicing equipment market also can be divided into: North America, Europe, Asia-Pacific, MEA (Middle East and Africa), Latin America.

The dicing equipment market is further segmented into blade dicing, laser ablation, stealth dicing, plasma dicing. According to the research, the blade dicing segment had the largest share in the global thin wafer processing and dicing equipment market.

Market Segmentation

By type: thinning equipment, dicing equipment

By wafer size: less than 4 inch, 5 inch and 6 inch, 8 inch, 12 inch

By application: memory and logic, MEMS device, power device, CMOS image sensor, RFID

By region: North America, Europe, Asia-Pacific, MEA (Middle East and Africa), Latin America

The global thin wafer processing and dicing equipment market report offers detailed information on several market vendors, including ASMPT Ltd, Disco Corporation, Han's Laser Technology Co., Ltd., KLA Corporation, Neon Tech Co., Ltd., Panasonic Corporation, Suzhou Delphi Laser Co., Ltd., Tokyo Seimitsu Co., Ltd., among others.

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Historical & Forecast Period

This research report provides analysis for each segment from 2018 to 2028 considering 2021 to be the base year.

Scope of the Report

To analyze and forecast the market size of the global thin wafer processing and dicing equipment market.

To classify and forecast the global thin wafer processing and dicing equipment market based on type, wafer size, application, region.

To identify drivers and challenges for the global thin wafer processing and dicing equipment market.

To examine competitive developments such as mergers & acquisitions, agreements, collaborations and partnerships, etc., in the global thin wafer processing and dicing equipment market.

To identify and analyze the profile of leading players operating in the global thin wafer processing and dicing equipment market.

Why Choose This Report

Gain a reliable outlook of the global thin wafer processing and dicing equipment market forecasts from 2022 to 2028 across scenarios.

Identify growth segments for investment.

Stay ahead of competitors through company profiles and market data.

The market estimate for ease of analysis across scenarios in Excel format.

Strategy consulting and research support for three months.

Print authentication provided for the single-user license.

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5 inch and 6 inch
8 inch
12 inch

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MEMS device
Power device

CMOS image sensor
RFID

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North America
Europe
Asia-Pacific
MEA (Middle East and Africa)
Latin America

PART 9. KEY COMPANIES

ASMPT Ltd
Disco Corporation
Han's Laser Technology Co., Ltd.
KLA Corporation
Neon Tech Co., Ltd.
Panasonic Corporation
Suzhou Delphi Laser Co., Ltd.
Tokyo Seimitsu Co., Ltd.
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